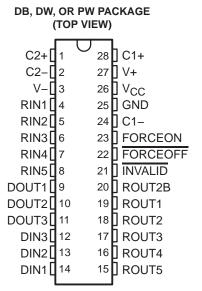
SN65C3243, SN75C3243 3-V TO 5.5-V MULTICHANNEL COMPATIBLE RS-232 LINE DRIVERS/RECEIVERS

SLLS353D - JUNE 1999 - REVISED MARCH 2004

- Operate With 3-V to 5.5-V V_{CC} Supply
- Always-Active Noninverting Receiver Output (ROUT2B)
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accept 5-V Logic Input With 3.3-V Supply
- Inter-Operable With SN65C3238, SN75C3238
- Support Operation From 250 kbit/s to 1 Mbit/s
- RS-232 Bus-Pin ESD Protection Exceeds ±15-kV Using Human-Body Model (HBM)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment



description/ordering information

The SN65C3243 and SN75C3243 consist of three line drivers, five line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin-to-pin (serial-port connection pins, including GND). These devices provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, these devices include an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the devices are powered down. The devices operate at data signaling rates up to 1 Mbit/s and an increased slew-rate range of 24 V/ μ s to 150 V/ μ s.

ORDERING INFORMATION

TA	PACKAG	iņ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 (D)40	Tube of 20	SN75C3243DW	7500040
	SOIC (DW)	Reel of 1000	SN75C3243DWR	75C3243
-0°C to 70°C	SSOP (DB)	Reel of 2000	SN75C3243DBR	75C3243
	TCCOD (DM)	Tube of 50	SN75C3243PW	040040
	TSSOP (PW)	Reel of 2000	SN75C3243PWR	CA3243
	0010 (D)40	Tube of 20	SN65C3243DW	0500040
	SOIC (DW)	Reel of 1000	SN65C3243DWR	65C3243
-40°C to 85°C	SSOP (DB)	Reel of 2000	SN65C3243DBR	65C3243
	TCCOD (DM)	Tube of 50	SN65C3243PW	0502042
	TSSOP (PW)	Reel of 2000	SN65C3243PWR	65C3243

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the devices do not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 µA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when FORCEON and FORCEOFF are high and should be done when driving a serial mouse. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 μs. INVALID is low (invalid data) if all receiver input voltages are between –0.3 V and 0.3 V for more than 30 μs. Refer to Figure 5 for receiver input levels.

Function Tables

EACH DRIVER

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

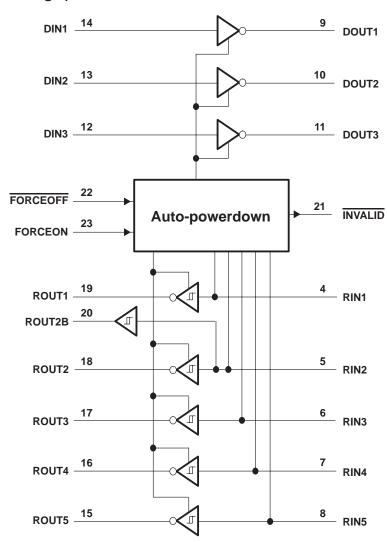
EACH RECEIVER

		INPUTS		OUTP	UTS	
RIN2	RIN1, RIN3–RIN5	FORCEOFF	VALID RIN RS-232 LEVEL	ROUT2B	ROUT	RECEIVER STATUS
L	Х	L	Х	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT2B is active
L	L	Н	Yes	L	Н	
L	Н	Н	Yes	L	L	Normal operation with
Н	L	Н	Yes	Н	Н	auto-powerdown
Н	Н	Н	Yes	Н	L	disabled/enabled
Open	Open	Н	No	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	–0.3 V to 7 V
Negative output supply voltage range, V- (see Note 1)	0.3 V to -7 V
Supply voltage difference, V+ – V– (see Note 1)	
Input voltage range, V _I : Driver (FORCEOFF, FORCEON)	–0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, V _O : Driver	–13.2 V to 13.2 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	62°C/W
DW package	46°C/W
PW package	62°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Ownerhouseltenes		V _C C = 3.3 V	3	3.3	3.6	
	Supply voltage		V _{CC} = 5 V	4.5	5	5.5	>
	Debugger and a control black board for an extraction	DIN FORCES FORCES	V _{CC} = 3.3 V	2			
VIH	Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V _C C = 5 V	2.4			>
V_{IL}	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				0.8	V
٧ _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
VI	Receiver input voltage			-25		25	V
_	On another for a sintense continu		SN65C3243	-40		85	20
TA	Operating free-air temperature		SN75C3243	0		70	°C

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMI	ETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
Ц	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON = V_{CC}		0.3	1	mA
		Powered off	No load, FORCEOFF = GND		1	10	
lcc	Supply current	Auto-powerdown enabled	No load, FORCEOFF = V _{CC} , FORCEON = GND, All RIN are open or grounded, All DIN are grounded		1	10	μΑ

[‡] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TE	ST CONDITION	S	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	o GND		5	5.4		V
VOL	Low-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	o GND		-5	-5.4		V
Vo	Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DII 3-k Ω to GND at DOUT3, DOUT1 = DOUT2 = 2.5			±5			V
lіН	High-level input current	VI = VCC				±0.01	±1	μΑ
Ι _Ι Γ	Low-level input current	V _I = GND				±0.01	±1	μΑ
		VCC = 3.6 V,	VO = 0 V			±35	±60	4
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V			±35	±75	mA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V,	V _O = ±2 V		300	10M		Ω
1	Output lookaga aurrant	FORCEOFF = GND	$V_0 = \pm 12 \text{ V},$	V _{CC} = 3 V to 3.6 V			±25	^
loff	Output leakage current	FORGEOFF = GND	$V_0 = \pm 10 \text{ V},$	V _{CC} = 4.5 V to 5.5 V			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	1	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
			C _L = 1000 pF		250			
	Maximum data rate (see Figure 1)	$R_L = 3 \text{ k}\Omega$, One DOUT switching	$C_L = 250 pF$,	$V_{CC} = 3 V \text{ to } 4.5 V$	1000			kbit/s
	(See Figure 1)	One Boot switching	$C_L = 1000 pF$,	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	1000			
tsk(p)	Pulse skew§	$C_L = 150 \text{ pF to } 2500 \text{ pF},$	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	See Figure 2		25		ns
SR(tr)	Slew rate, transition region (see Figure 1)	C _L = 150 pF to 1000 pF,	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	V _{CC} = 3.3 V	24		150	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



^{\$\}frac{1}{2}\$ Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

[§] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
\/_	Desitive resident inner three held welters	V _{CC} = 3.3 V		1.6	2.4	
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	٧
.,	No and the material through addition to an	V _{CC} = 3.3 V	0.6	1.1		.,
V _{IT} _	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
l _{off}	Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_{I} = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	TYP [†]	UNIT
tPLH	Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 3	150	ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time	C_L = 150 pF, R_L = 3 k Ω , See Figure 4	200	ns
tdis	Output disable time	C_L = 150 pF, R_L = 3 k Ω , See Figure 4	200	ns
t _{sk(p)}	Pulse skew [‡]	See Figure 3	50	ns

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



NOTE 4. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

[‡] Pulse skew is defined as |tplH - tpHL| of each channel of the same device.

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
VT+(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}		2.7	V
VT-(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7		٧
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3	0.3	٧
VOH	INVALID high-level output voltage	$I_{OH} = -1 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}	V _{CC} - 0.6		٧
VOL	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCEON = GND, FORCEOFF = V _{CC}		0.4	V

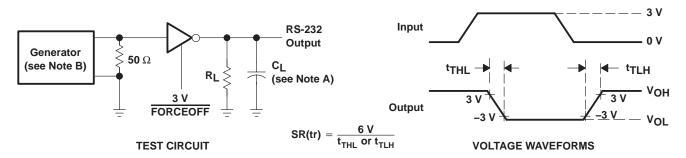
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TYP	UNIT
tvalid	Propagation delay time, low- to high-level output	1	μs
tinvalid	Propagation delay time, high- to low-level output	30	μs
ten	Supply enable time	100	μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.



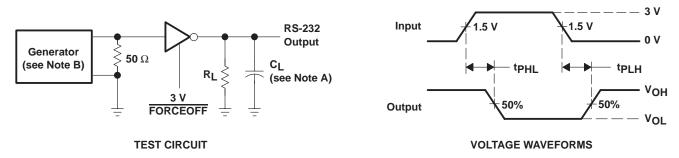
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 Mbit/s, Z_{Ω} = 50 Ω , 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

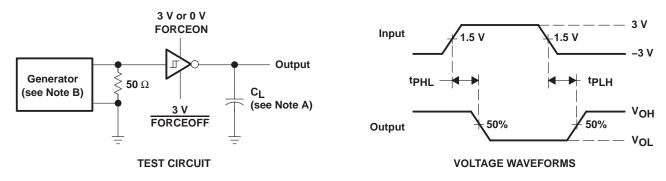
Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 Mbit/s, $Z_O = 50~\Omega$, 50% duty cycle, $t_f \le 10~\text{ns}$.

Figure 2. Driver Pulse Skew



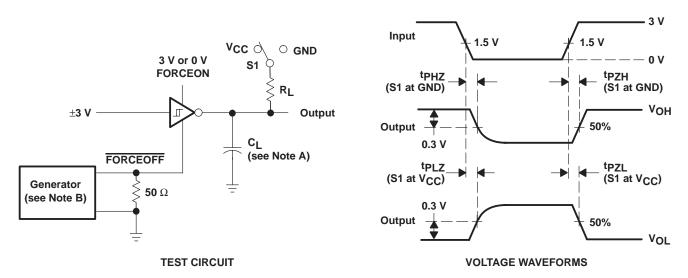
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

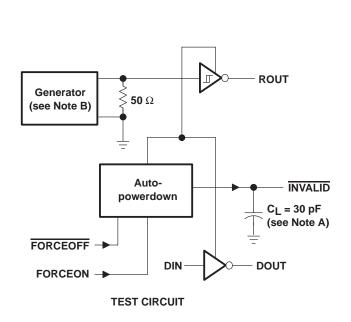
B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

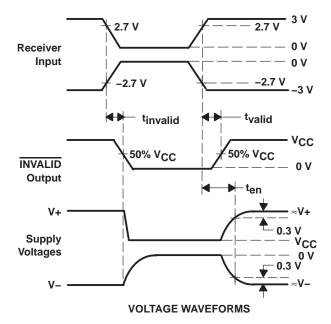
C. tpLz and tpHz are the same as tdis.

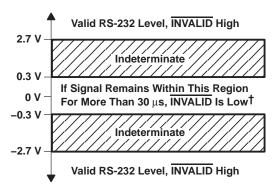
D. tpZL and tpZH are the same as ten.

Figure 4. Receiver Enable and Disable Times

PARAMETER MEASUREMENT INFORMATION







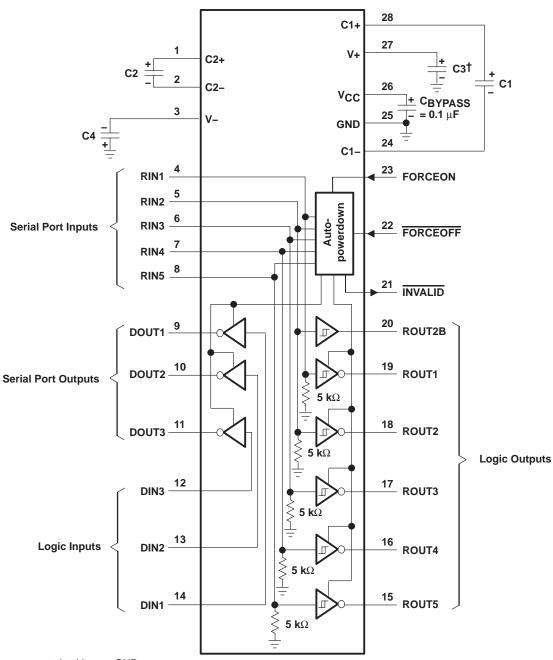
[†] Auto-powerdown disables drivers and reduces supply current to 1 μA.

NOTES: A. C_I includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION



†C3 can be connected to V_{CC} or GND. NOTE A: Resistor values shown are nominal.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

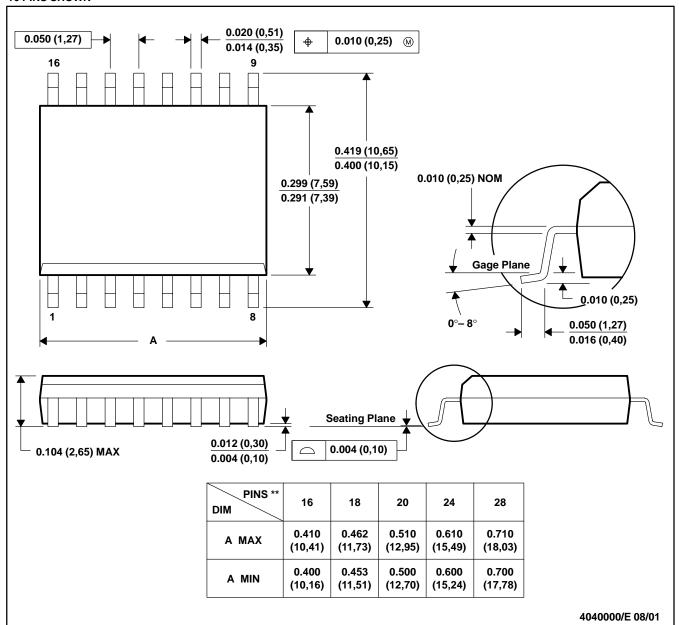
Figure 6. Typical Operating Circuit and Capacitor Values



DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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